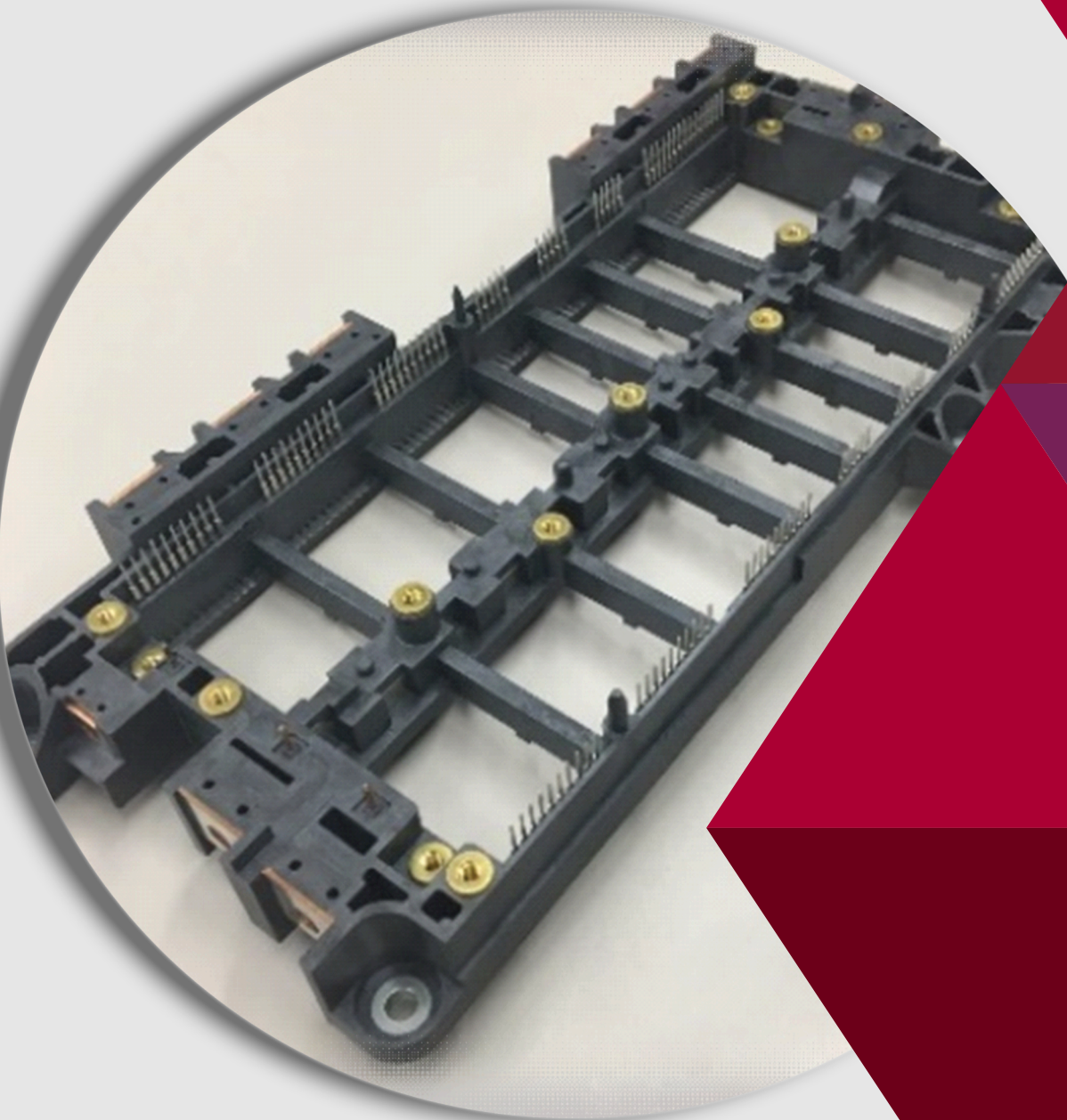




Materials for Power Devices and Electronic Components

Miniaturization and Weight Reduction for EV Applications



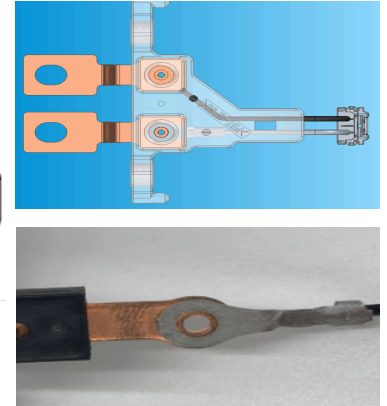
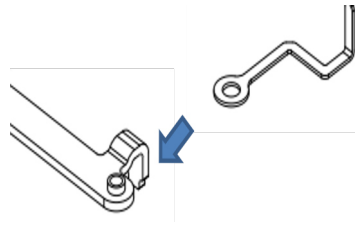
In-Mold Connecting Technology

Swaging technique in the insert molding process - the clamping press to connect and fasten busbar and wire is completed in molding process.

Features

- » Enabling to use a wide range of metals
- » Enable to use different sizes of thickness
- » Time & cost saving due to reduced connecting process

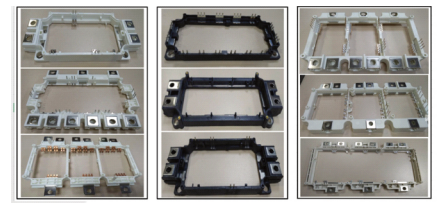
Application



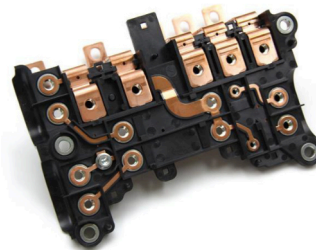
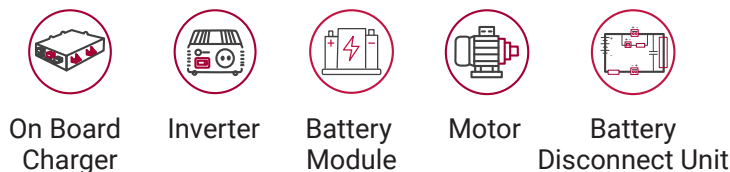
Metal Insert Mold

Features

- » Providing multiple resin and metal parts as an integrated product by insert molding
- » Providing multiple insert molded products
- » Designing good creepage distances for insulation but ensuring desired mold shape for your needs



Application



Ultra-Low Inductance Busbar

Features

- » Insulation design - 100 μm gap between busbars
- » Reducing parasitic inductance with PN terminals as close as possible
- » Insulation kept by film insert molding
- » Very effective for high-speed switching like SiC
- » Miniaturisation for module
- » Patent pending

Application

